





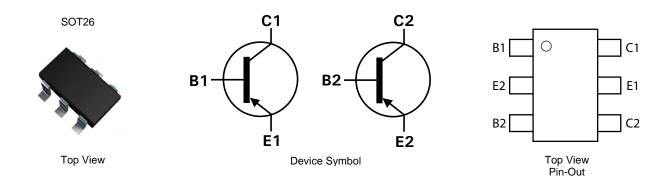
#### **60V DUAL PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR**

### **Features & Benefits**

- BV<sub>CEO</sub> > -60V
- I<sub>CM</sub> = -1A Peak Pulse Current
- General purpose NPN transistors ideally suited for low power amplification and switching applications
- Dual transistors in a single SOT26 package taking half the footprint of two equivalent transistors in SOT23
- Epitaxial planar die construction
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating: Matte Tin Finish annealed over Copper leadframe
- Weight: 0.015 grams (approximate)



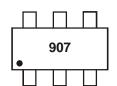
#### Ordering Information (Note 3)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMMT2907A-7	907	7	8	3,000

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com

## **Marking Information**



907 = Product Type Marking Code



# Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-60	V
Emitter-Base Voltage	V <sub>EBO</sub>	-5	V
Continuous Collector Current	Ic	-600	mA
Peak Pulsed Collector Current	I <sub>CM</sub>	-1	А

### Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Notes 5 & 6)		1.28 10.3	W	
Linear Derating Factor	(Notes 4 & 6)	P <sub>D</sub>	0.90 7.14	mW/°C	
Thermal Resistance, Junction to Ambient	(Notes 5 & 6) (Notes 4 & 6)	$R_{ heta JA}$	97 140	°C/W	
Thermal Resistance, Junction to Lead	(Note 7)	$R_{ heta JL}$	113		
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C		

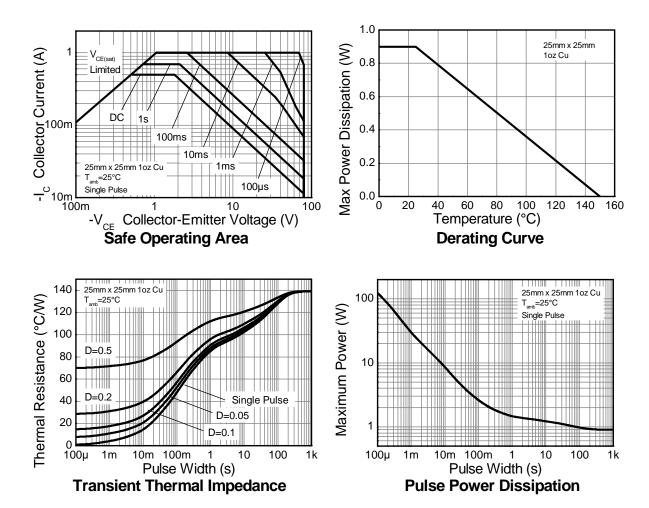
- 4. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is 4. For a device surface modified on 25mm x 25mm x 1.5mm FR4 FCB with high covered when operating in a steady-state condition.
  5. Same as note (4), except the device is measured at t ≤ 5 sec.
  6. For a dual device with one active die.
  7. Thermal resistance from junction to solder-point (at the end of the collector lead).

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### **Thermal Characteristics**





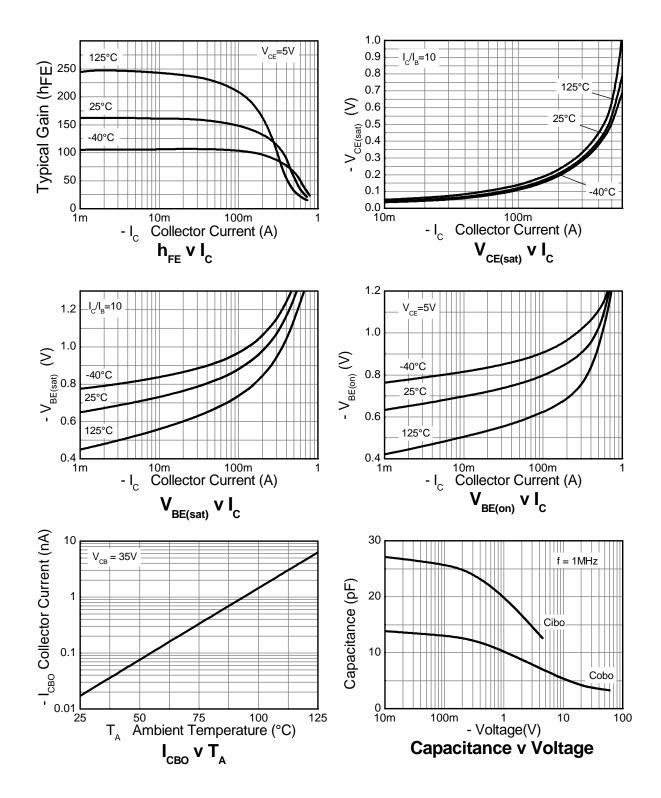
# Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-60			V	$I_C = -10\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage (Note 8)	BV <sub>CEO</sub>	-60			V	$I_C = -10 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-5			V	$I_E = -10\mu A, I_C = 0$	
Collector-Base Cutoff Current	I <sub>CBO</sub>			-10	nA	$V_{CB} = -50V, I_{E} = 0$	
Collector-base Cutoff Current				-10	μΑ	$V_{CB} = -50V$ , $I_E = 0$ , $T_A = 150$ °C	
Collector-Emitter Cutoff Current	I <sub>CEV</sub>			±50	nA	$V_{CE} = -30V, V_{BE} = \pm 0.25V$	
Base-Emitter Cutoff Current	I <sub>BEV</sub>		_	±50	nA	$V_{CE} = -30V, V_{BE} = \pm 0.25V$	
ON CHARACTERISTICS (Note 8)							
		75	_	_		$I_C = -100 \mu A, V_{CE} = -10 V$	
	ı İ	100	_	_		$I_C = -1.0 \text{mA}, V_{CE} = -10 \text{V}$	
DC Current Gain	h <sub>FE</sub>	100	_		_	$I_C = -10 \text{mA}, V_{CE} = -10 \text{V}$	
		100		300		$I_C = -150 \text{mA}, V_{CE} = -10 \text{V}$	
		50	_			$I_C = -500 \text{mA}, \ V_{CE} = -10 \text{V}$	
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	_		-0.4	٧	$I_C = -150 \text{mA}, I_B = -15 \text{mA}$	
Collector-Emitter Saturation Voltage		_		-1.6		$I_C = -500 \text{mA}, I_B = -50 \text{mA}$	
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	_		-1.3	V	$I_C = -150 \text{mA}, I_B = -15 \text{mA}$	
<u> </u>		_	_	-2.6		$I_C = -500 \text{mA}, I_B = -50 \text{mA}$	
SMALL SIGNAL CHARACTERISTICS							
Output Capacitance	$C_{obo}$	_	5.2	_	pF	$V_{CB} = -10V$ , $f = 1.0MHz$ , $I_E = 0mA$	
Input Capacitance	C <sub>ibo</sub>		16.3		pF	$V_{EB} = -2.0V$ , $f = 1.0MHz$ , $I_{C} = 0mA$	
Current Gain-Bandwidth Product	f <sub>T</sub>	200	307		MHz	$V_{CE} = -2V$ , $I_{C} = -10mA$ , $f = 100MHz$	
Turn-On Time	t <sub>on</sub>			21	ns	$V_{CC} = -30V I_C = -150mA,$ $I_{B1} = -15mA$	
Delay Time	t <sub>d</sub>		_	5.5	ns		
Rise Time	t <sub>r</sub>		_	15.3	ns		
Turn-Off Time	t <sub>off</sub>		_	200	ns	V <sub>CC</sub> = -6V	
Storage Time	ts		_	160	ns	$V_{CC} = -6V$ $I_{C} = -150\text{mA}, I_{B1} = I_{B2} = -15\text{mA}$	
Fall Time	t <sub>f</sub>			40	ns	IC = -130IIIA, IB1 = IB2 = -13IIIA	

Notes: 8. Measured under pulsed conditions. Pulse width  $\leq 300 \mu s$ . Duty cycle  $\leq 2\%$ .

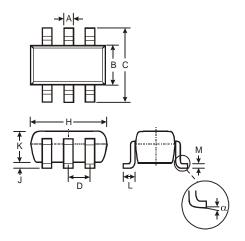


## **Typical Electrical Characteristics**



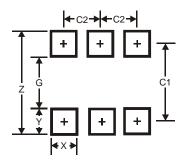


## **Package Outline Dimensions**



SOT26					
Dim	Min	Max	Тур		
Α	0.35	0.50	0.38		
В	1.50	1.70	1.60		
С	2.70	3.00	2.80		
D	_	_	0.95		
Н	2.90	3.10	3.00		
J	0.013	0.10	0.05		
K	1.00	1.30	1.10		
L	0.35	0.55	0.40		
M	0.10	0.20	0.15		
α	0°	8°	_		
All Dimensions in mm					

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

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